

1206L Series

NEW



- Complies with electronic industry environmental standards for lead reduction.

PHYSICAL SPECIFICATIONS:

Terminal Material: Tin Plated Copper

Device Labeling: Device is marked with amperage rating code.

AGENCY APPROVALS: Recognized under the Components Program of Underwriters Laboratories and the Acceptance program of CSA. TUV approved.

AGENCY FILE NUMBERS: UL E183209, CSA LR108832.

ENVIRONMENTAL SPECIFICATIONS:

Passive Aging: 85°C, 1000 Hours.

Humidity Aging: 85°C, 85% R.H., 100 hours.

Thermal Shock: 85°C / -40°C, 20 times.

Vibration: MIL-STD 202, Method 201, MIL-STD-883, Method 2007.

Mechanical Shock: MIL-STD-202, Method 213 test condition I (100 g's, 6 sec.).

Solvent Resistance: MIL-STD-202, Method 215.

Operating/Storage Temperature: -40°C to 85°C

Device should remain in sealed bags prior to use.

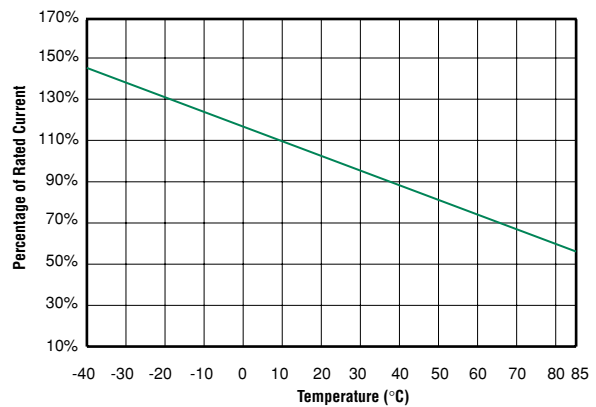
Temperature Derating:

Packaging: 8mm tape and reel carrier per EIA 481 Standard.

Standard reel quantities: 0.20-0.35A: 4,000 devices on 7" reel (YRT Suffix).

0.50-1.50A: 3,000 devices on 7" reel (WRT Suffix).

Temperature Derating Curve:

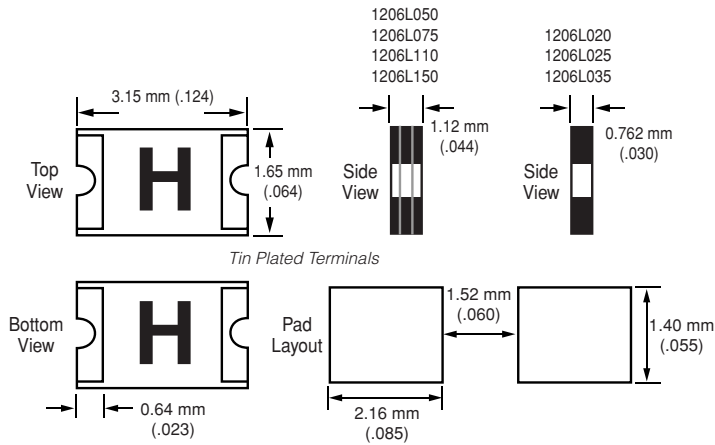


Part Number	Ambient Temperature									
	-40°C	-20°C	0°C	20°C	40°C	50°C	60°C	70°C	80°C	85°C
1206L020	0.29	0.26	0.23	0.20	0.17	0.16	0.14	0.13	0.11	0.10
1206L025	0.36	0.33	0.29	0.25	0.21	0.20	0.18	0.16	0.14	0.13
1206L035	0.51	0.46	0.40	0.35	0.30	0.27	0.25	0.22	0.20	0.18
1206L050	0.74	0.67	0.59	0.50	0.44	0.40	0.36	0.32	0.28	0.26
1206L075	1.11	1.00	0.89	0.75	0.65	0.59	0.54	0.48	0.42	0.39
1206L110	1.63	1.46	1.30	1.10	0.96	0.87	0.79	0.70	0.62	0.57
1206L150	2.22	2.00	1.77	1.50	1.31	1.19	1.08	0.96	0.84	0.78

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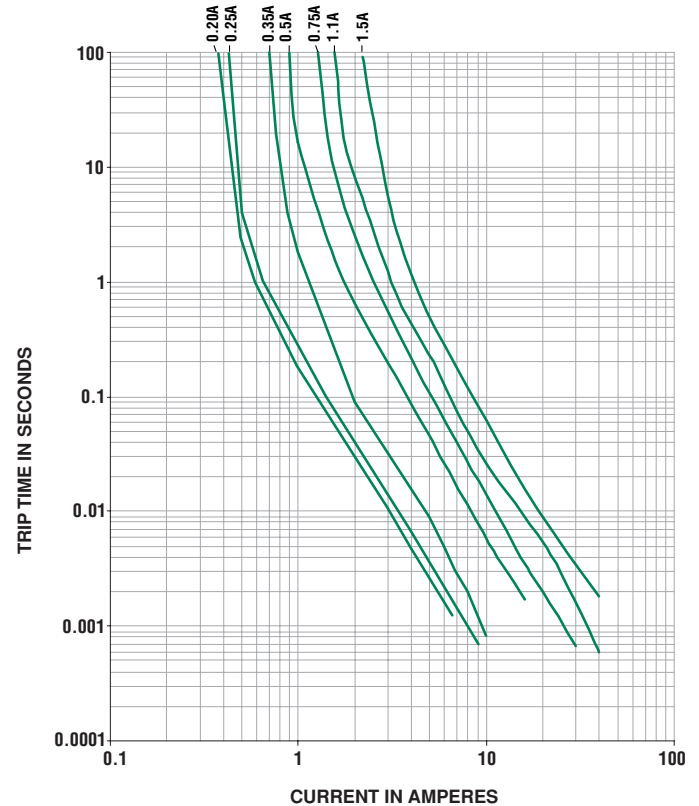
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Dimensions (Inches)



Recommended Pad Layout (Inches)
All dimensions are nominal.

Average Time Current Curves



Solderability: Meets EIA specification RS186-9E and IPC/EIA J-STD-002, and IPC/EIA J-STD-001.

Soldering Parameters:

Reflow Solder — 245°C, 20 seconds maximum
Wave Solder — 245°C, 10 seconds maximum

Electrical Characteristics:

Part Number	Marking Code	I_{Hold} (A)	I_{Trip} (A)	V_{Max} (V _{dc})	I_{Max} (A)	Maximum Time To Trip			R_{IL} (Ω)	R_{AT} (Ω)
						P_d max. (W)	Current (A)	Time (Sec)		
1206L020	C	0.20	0.40	15.0	40	0.8	8.0	0.05	0.600	2.500
1206L025	D	0.25	0.50	15.0	40	0.8	8.0	0.08	0.550	2.300
1206L035	E	0.35	0.70	6.0	40	0.8	8.0	0.10	0.300	1.300
1206L050	F	0.50	1.00	6.0	40	0.8	8.0	0.10	0.090	0.600
1206L075	G	0.75	1.50	6.0	40	0.8	8.0	0.20	0.070	0.300
1206L110	H	1.10	2.20	6.0	40	0.8	8.0	0.30	0.040	0.180
1206L150	K	1.50	3.00	6.0	40	0.8	8.0	0.30	0.030	0.120

I_{hold} = Hold Current: maximum current device will sustain for 4 hours without tripping in 20°C still air.
 I_{trip} = Trip Current: minimum current at which the device will trip in 20°C still air.
 V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})
 I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})
 P_d = Power dissipated from device when in the tripped state at 20°C still air.
 R_{IL} = Minimum resistance of device in initial (un-soldered) state.
 R_{AT} = Maximum measured resistance in the non-tripped state 1 hour after reflow with reflow conditions of 245°C for 20 sec.

CAUTION: Operation beyond the specified ratings may result in damage and possible arcing and flame.